

Zarlink and Redux Announce Interoperability and Compliance with Metro Ethernet Circuit Emulation Standards at SUPERCMM 2004

Companies demonstrate interoperability of products based on draft MEF (Metro Ethernet Forum) CESoE (Circuit Emulation Services over Ethernet) specifications

CHICAGO, ILLINOIS, June 22, 2004 – Zarlink Semiconductor (NYSE/TSX:ZL) and Redux Communications today announced successful interoperability testing for E1/T1 circuit connectivity over Ethernet/IP networks. Zarlink and Redux, both members of the Metro Ethernet Forum (www.metroethernetforum.org), will be demonstrating interconnectivity in the MEF SUPERDemo Booth #20736 at SUPERCMM, June 22 to 24 in Chicago.

The interoperability tests involve Zarlink's ZL™50111 TDM-over-IP packet processor and Redux Communications' Arranto 100TE multi-service TDM-over-Packet Gateway, which is based on the Redux TDM-over-Packet RS-160 ASSP.

The testing is based on the companies' respective implementations of the draft MEF CESoE specification for Layer 2 Ethernet networks. Zarlink and Redux are also demonstrating interoperability of the related ITU-T (International Telecommunications Union-Telecommunications) recommendation Y.1413, and the IETF (International Engineering Task Force) draft standards for SAToP (Structure Agnostic TDM-over-Packet) and CESoPSN (Circuit Emulation Services over Packet Switched Networks). Y.1413 was ratified by the ITU-T in April 2004, and the SAToP and CESoPSN standards are in the final stages of ratification by the IETF.

"A growing number of network applications, from passive optical networks, wireless basestation and digital loop carrier backhaul, to wireless broadband access, are using TDM-over-IP technology," said Jeremy Lewis, product line marketing manager, Zarlink Semiconductor. "Ethernet is increasingly pervasive and TDM-over-IP offers a seamless transition for carriers, enterprises and consumers."

"Demand is rapidly growing for standards-based solutions to transparently connect TDM equipment over Metro Ethernet and other packet infrastructures," said Daniel Bar-Lev, vice president of marketing at Redux Communications. "As the two leading vendors of TDM-over-Packet solutions, Redux and Zarlink attach prime importance to implementing and promoting industry standards and specifications for E1/T1 over Ethernet/IP applications."

Zarlink's ZL50111 processors utilize CESoP (Circuit Emulation Services over Packet) technology to cost-effectively "tunnel" TDM traffic through any type of IP/Ethernet/MPLS network, and transport up to 32 T1/E1 TDM circuits and two T3/E3 TDM circuits across a packet-switched network.

Redux Communications offers system, module and semiconductor multi-service gateway solutions for transporting multiple E1/T1 circuits and serial HDLC/bitstream data over Ethernet/IP networks utilizing Redux's leading 100 Mbps network processor technology.

About Zarlink Semiconductor

For almost 30 years, Zarlink Semiconductor has delivered semiconductor solutions that drive the capabilities of voice, enterprise, broadband and wireless communications. The Company's success is built on its technology strengths, including voice and data networks, consumer and ultra low-power communications, and high-performance analog. For more information, visit www.zarlink.com.

About Redux Communications

Redux is the leading provider of standards-compliant system, OEM and semiconductor solutions for Multi-Service over Packet applications, for CLE and packet network edge deployment. Redux solutions are based on the company's proprietary silicon technology developed to support high performance, converged voice and data applications over Ethernet or IP infrastructure. Based in Modi'in, Israel, Redux has a worldwide presence and markets its products in the Americas, Europe and Asia. For more information, visit www.reduxcom.com.

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